Overview

The purpose of this notification is to announce conversion of substrate material changed from BT to ABF build-up for selected Aerospace & Defense ‘XQ’ Virtex-4 FPGA device/package. There is no change to the form, fit, function or reliability with this change.

Description

For the below affected products, substrate materials will be converted from BT to ABF build-up. The reason for the change is the phase out of UV laser equipment support at substrate supplier. To ensure continuity of supply for flip chip products, BT will be replaced by ABF since UV laser is not required to form vias with ABF material. The ABF materials set is already qualified and in production for other Virtex-II Pro FPGA, Virtex-4 FPGA and Virtex-5 FPGA products.

Products Affected

This change affects all speed, package, and temperature variations of the Aerospace & Defense ‘XQ’ devices. Affected part numbers are included in the following table(s):

Table 1: Product Changes

<table>
<thead>
<tr>
<th>Xilinx Product</th>
<th>Package</th>
<th>Change Description</th>
</tr>
</thead>
<tbody>
<tr>
<td>XQ4VLX40</td>
<td>FF(G)668</td>
<td>Build-up materials set change from BT to ABF</td>
</tr>
<tr>
<td>XQ4VLX100</td>
<td>FF(G)1148</td>
<td>Build-up materials set change from BT to ABF</td>
</tr>
</tbody>
</table>

Key Dates and Ordering Information

Xilinx will begin to ship production using ABF substrate materials on or after 25th January 2010 (90 days of PCN date).

Qualification Data

Qualification data & device reliability report for Virtex-4 FPGA devices is available in the UG116. The extended qualification data related to this PCN is available in the RPT141.
Response

No response is required. For additional information or questions, please contact Xilinx Technical Support.

Important Notice: Xilinx Customer Notifications (XCNs, XDNs, and Quality Alerts) can be delivered via e-mail alerts sent by the MySupport website (http://www.xilinx.com/support). Register today and personalize your “MyAlerts” area to include Customer Notifications. This change provides many benefits, including the ability to receive alerts for new and updated information about specific products, as well as alerts for other publications such as data sheets, errata, application notes, etc. For information on how to sign up, refer to Xilinx Answer Record 18683.

Additional Documentation

Qualification Report (RPT141)
https://secure.xilinx.com/webreg/clickthrough.do?cid=140202


Revision History

The following table shows the revision history for this document.

<table>
<thead>
<tr>
<th>Date</th>
<th>Version</th>
<th>Revision</th>
</tr>
</thead>
<tbody>
<tr>
<td>10/26/09</td>
<td>1.0</td>
<td>Initial release.</td>
</tr>
</tbody>
</table>

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